

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Rey H. Bruce</td><td>11/30/2006</td></tr><tr><td>Ricardo H. Bruce</td><td>11/29/2006</td></tr><tr><td>Patrick Digamon Bugayong</td><td>11/29/2006</td></tr><tr><td>Joel Alonzo Baylon</td><td>11/29/2006</td></tr></tbody></table>		Name	Execution Date	Rey H. Bruce	11/30/2006	Ricardo H. Bruce	11/29/2006	Patrick Digamon Bugayong	11/29/2006	Joel Alonzo Baylon	11/29/2006
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Ricardo H. Bruce	11/29/2006										
Patrick Digamon Bugayong	11/29/2006										
Joel Alonzo Baylon	11/29/2006										
RECEIVING PARTY DATA											
Name:	BITMICRO NETWORKS, INC.										
Street Address:	47929 Fremont Blvd										
City:	Fremont										
State/Country:	CALIFORNIA										
Postal Code:	94538										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11322442</td></tr></tbody></table>		Property Type	Number	Application Number:	11322442						
Property Type	Number										
Application Number:	11322442										
CORRESPONDENCE DATA											
Fax Number: (408)716-2651 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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ATTORNEY DOCKET NUMBER:	6005.011										
NAME OF SUBMITTER:	Stephen R. Uriarte										

OP \$40.00 11322442

**Total Attachments: 4**

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**PATENT**

**REEL: 018594 FRAME: 0241**

**ASSIGNMENT**

For good and valuable consideration, the receipt of which is hereby acknowledged, the person(s) named below (referred to as "INVENTOR" whether singular or plural) has sold, assigned, and transferred and does hereby sell, assign, and transfer to **BiTMICRO Networks, Inc., a California corporation, having a place of business at 47929 Fremont Blvd., Fremont, CA 94538** ("ASSIGNEE"), for itself and its successors, transferees, and assignees, the following:

1. The entire worldwide right, title, and interest in all inventions and improvements ("SUBJECT MATTER") that are disclosed in the application for United States Letters Patent entitled: **Multiple Chip Module and Package Stacking Method for Storage Devices** ("APPLICATION"), which:

☐ is to be filed herewith

☒ was filed on **December 29, 2005**, now bearing U.S. serial number **11/322,442** and for which a Declaration was executed by INVENTOR on the date(s) below; and

2. The entire worldwide right, title, and interest in and to: (a) the APPLICATION, including any right of priority; (b) any divisional, continuation, substitute, renewal, reissue, and other related applications thereto which have been or may be filed in the United States or elsewhere in the world; and (c) any patents which may be granted on the applications set forth in (a) and (b) above.

INVENTOR agrees that ASSIGNEE may apply for and receive patents for SUBJECT MATTER in ASSIGNEE's own name.

INVENTOR agrees to do the following, when requested, and without further consideration, in order to carry out the intent of this Assignment: (1) execute all oaths, assignments, powers of attorney, applications, and other papers necessary or desirable to fully secure to ASSIGNEE the rights, titles and interests herein conveyed; (2) communicate to ASSIGNEE all known facts relating to the SUBJECT MATTER; and (3) generally do all lawful acts that ASSIGNEE shall consider desirable for securing, maintaining, and enforcing worldwide patent protection relating to the SUBJECT MATTER and for vesting in ASSIGNEE the rights, titles, and interests herein conveyed. INVENTOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE hereunder.

INVENTOR represents that INVENTOR has the rights, titles, and interests to convey as set forth herein, and covenants with ASSIGNEE that the INVENTOR has made or will make hereafter no assignment, grant, mortgage, license, or other agreement affecting the rights, titles, and interests herein conveyed.


INVENTOR grants the attorney of record the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.


Title of Document: **ASSIGNMENT**  
 In Re Application of: Bruce et al.  
 Title: Multiple Chip Module and Package Stacking Method for Storage  
 Devices  
 Filed: (if applicable) December 29, 2005  
 Serial No.: (if applicable) 11/322,442


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This Assignment may be executed in one or more counterparts, each of which shall be deemed an original and all of which may be taken together as one and the same Assignment.

<u>Inventor Signature</u> .....	<u>Date of Signature</u>	<u>Date Invention Declaration Signed by Inventor</u>
.....	....., 2006	December 20, 2005
Printed Name: Rey H. Bruce		

<u>Inventor Signature</u> .....	<u>Date of Signature</u>	<u>Date Invention Declaration Signed by Inventor</u>
 .....	NOVEMBER 24, 2006	December 20, 2005
Printed Name: Ricardo H. Bruce		

<u>Inventor Signature</u> .....	<u>Date of Signature</u>	<u>Date Invention Declaration Signed by Inventor</u>
 .....	NOVEMBER 29, 2006	December 20, 2005
Printed Name: Patrick Digamon Bugayang		

<u>Inventor Signature</u> .....	<u>Date of Signature</u>	<u>Date Invention Declaration Signed by Inventor</u>
 .....	NOVEMBER 27, 2006	December 20, 2005
Printed Name: Joel Alonzo Baylon		

ASSIGNMENT

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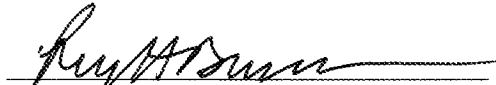
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<u>Inventor Signature</u>	<u>Date of Signature</u>	<u>Date Invention Declaration Signed by Inventor</u>
 Printed Name: Rey H. Bruce	<u>11-30</u> , 2006	December 20, 2005

<u>Inventor Signature</u>	<u>Date of Signature</u>	<u>Date Invention Declaration Signed by Inventor</u>
  Printed Name: Ricardo H. Bruce	, 2006	December 20, 2005

<u>Inventor Signature</u>	<u>Date of Signature</u>	<u>Date Invention Declaration Signed by Inventor</u>
  Printed Name: Patrick Digamon Bugayong	, 2006	December 20, 2005

<u>Inventor Signature</u>	<u>Date of Signature</u>	<u>Date Invention Declaration Signed by Inventor</u>
  Printed Name: Joel Alonzo Baylon	, 2006	December 20, 2005